

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yen-Cheng Lu</td> <td>09/02/2013</td> </tr> <tr> <td>Shinn-Sheng Yu</td> <td>09/02/2013</td> </tr> <tr> <td>Jeng-Hong Chen</td> <td>09/02/2013</td> </tr> <tr> <td>Anthony Yen</td> <td>09/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yen-Cheng Lu	09/02/2013	Shinn-Sheng Yu	09/02/2013	Jeng-Hong Chen	09/02/2013	Anthony Yen	09/02/2013
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000 Email: ipdocketing@haynesboone.com Correspondent Name: HAYNES AND BOONE, LLP IP Section Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>											
ATTORNEY DOCKET NUMBER:	24061.2577										
NAME OF SUBMITTER:	Linda Ingram										
Signature:	/Linda Ingram/										

PATENT

Date:

09/06/2013

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|----------------------------------------------------------------------------------------------------|
| (1) | Yen-Cheng Lu | of | 2F., No. 12, Ln. 31, Sec. 1, Sanmin Road
Banqiao District
New Taipei City 220, Taiwan R.O.C. |
| (2) | Shinn-Sheng Yu | of | 4F-2, No. 16, Lane 634, Nanda Road
Hsinchu, Taiwan R.O.C. |
| (3) | Jeng-Horng Chen | of | 1, Alley 2, Lane 45, Fu-Chyun Street
Hsin-Chu, Taiwan, R.O.C. |
| (4) | Anthony Yen | of | 20F-9, 188 Guanxin Road
Hsinchu 300, Taiwan R.O.C. |

have invented certain improvements in

AN EXTREME ULTRAVIOLET LITHOGRAPHY PROCESS AND MASK

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on September 6, 2013, and assigned application number 14/020,302; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2013-0622/24061.2577

Customer No.: 000042717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yen-Cheng Lu

Residence Address: 2F., No. 12, Ln. 31, Sec. 1, Sanmin Road, Banqiao District
New Taipei City 220, Taiwan R.O.C.

Dated: 09/02/2013

Yen-Cheng Lu
Inventor Signature

Inventor Name: Shinn-Sheng Yu

Residence Address: 4F-2, No. 16, Lane 634, Nanda Road, Hsinchu, Taiwan, R.O.C.

Dated: 09/02/2013

Shinn-Sheng Yu
Inventor Signature

Inventor Name: Jeng-Horng Chen

Residence Address: 1, Alley 2, Lane 45, Fu-Chyun Street, Hsin-Chu, Taiwan, R.O.C.

Dated: Sep 2, 2013

Jenghorng Chen
Inventor Signature

Docket No.: 2013-0622/24061.2577
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Inventor Name: Anthony Yen

Residence Address: 20F-9, 188 Guanxin Road, Hsinchu 300, Taiwan R.O.C.

Dated: Sept. 2, 2013


Inventor Signature